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| Project | **Human Factor for Immersive Content Working Group**<<http://sites.ieee.org/sagroups-3079/> **>** |
| Title | **IEEE MOU Organization MOU Request with ICF (Intelligent Contents Standardization Forum)** |
| DCN | **3079-23-0071-03-0000** |
| Date Submitted | **Oct. 19, 2023** |
| Source(s) | **Jun Young Kwak,** **weekendmeta@gmail.com**(HSU)**HyunDuck Shin,** **henry@hansung.ac.kr** (HSU) |
| Re: | Session #28, Tokyo, Japan |
| Abstract | This document is a draft for signing an MOU between the ICF (Intelligent Contents Standardization Forum) and the IEEE 3079 WG. |
| Purpose | The purpose of this document is to sign an MOU between the ICF (Intelligent Contents Standardization Forum) and the IEEE 3079 WG. |
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**Request for Establishment of External MOU**

**between the IEEE 3079 and Intelligent Contents Standardization Forum**

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| **Category** | External MOU with IEEE 3079 |
| **MOU Organization** | **Intelligent Contents Standardization Forum**Web: None**Contact person**: JunYoung KwakCompany: Hansung UniversityAddress: [02876] #106, Sangsangcube, 116, Samseonghyo-ro 16-gil, Seongbuk-gu, Seoul, KoreaEmail: weekendmeta@gmail.com |
| **MOU Representative** **of Intelligent Contents Standardization Forum** | Name: Mr. Kwak, JunYoungCompany: Hansung UniversityEmail: weekendmeta@gmail.com |
| **MOU Representative** **of IEEE 3079** | Name: Beom-Ryeol LeeCompany: ETRIEmail: lbr@etri.re.kr |
| **IEEE's Approval** | To be determined after IEEE internal discussion |
| **MOU Period** | One year after signing |
| **Statement of Expected Benefits and Responsibilities** | The MOU will bring efficiency in communications between the two organizations and contribute to a better understanding and implementation of interfaces between the cyber and physical worlds. Both organizations can give some feedback to the corresponding organization after reviewing the drafts and the standard text during the standard development process.The communications between both organizations cover the subjects of standard issues and sharing information on industrial trends as global technology has developed. In addition, it is available for members of each organization to attend the official meetings of the other organization as per MOU and to make a more worldwide network.We believe there are mutual responsibilities to collaborate between the two organizations. Each party is responsible for respecting the rules specified in each standard organization. During the standardization, it is necessary to ensure that the appropriate procedures for the official processing are followed. |

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| **IEEE 3079 WG** |  | **Intelligent Contents Standardization Forum** |
| *Dated:* |  | *Dated:* |
| 19-Oct. 2023 |  | 19-Oct. 2023 |
|  |  |  |
| *Signature:* |  | *Signature:* |
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